

Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	100 Sn
MS Number	MS011104A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.81E-02	87.7	877000	53.56		535589
Thermosets	Phenol Resin	Proprietary	1.74E-03	4.0	40000	2.44		24428
Thermosets	Epoxy Resin 1	Proprietary	1.30E-03	3.0	30000	1.83		18321
Thermosets	Epoxy Resin 2	Proprietary	1.52E-03	3.5	35000	2.14		21375
Others	Others	Proprietary	6.52E-04	1.5	15000	0.92		9161
Other inorganic materials	Carbon Black	1333-86-4	1.30E-04	0.3	3000	0.18		1832
Subtotal			4.35E-02	100.00	1000000	61.07		610706

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.09 E-02	97.5	975000	29.35		293532
Copper & its alloys	Iron	7439-89-6	5.04 E-04	2.35	23500	0.71		7075
Copper & its alloys	Zinc	7440-66-6	2.57 E-05	0.12	1200	0.04		361
Copper & its alloys	Phosphorus	7723-14-0	6.43 E-06	0.03	300	0.01		90
Subtotal			2.14 E-02	100.00	1000000	30.11		301058

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.17E-04	100.0	1000000	0.30		3041

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.22 E-03	100.0	1000000	1.71		17130

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	2.68 E-04	99.99	1000000	0.38		3760

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.35 E-03	100.0	1000000	3.30		32967

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.77 E-04	77.00	770000	1.09		10907
Other organic materials	Acrylic resin	Proprietary	7.06 E-05	7.00	70000	0.10		992
Other organic materials	Acrylate	Proprietary	5.55 E-05	5.50	55000	0.08		779
Other organic materials	Polybutadiene derivative	Proprietary	4.54 E-05	4.50	45000	0.06		637
Thermoset	Epoxy resin	Proprietary	2.52 E-05	2.50	25000	0.04		354
Other organic materials	Butadiene Copolymer	Proprietary	1.51 E-05	1.50	15000	0.02		212
Others	Additive	Proprietary	1.51 E-05	1.50	15000	0.02		212
Others	Peroxide	Proprietary	5.04 E-06	0.50	5000	0.007		71
Subtotal			1.01 E-03	100.0	1000000	1.42		14165

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other organic materials	Dimethylsiloxane	68083-19-2	7.39 E-04	60.4	604000	1.0		10372
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	3.42 E-04	28.0	280000	0.5		4808
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	1.22 E-04	10.0	100000	0.2		1717
Other organic materials	Ethylbenzene	100-41-4	1.22 E-05	1.0	10000	0.02		172
Other organic materials	Xylene	1330-20-7	7.34 E-06	0.6	6000	0.01		103
Subtotal			1.22 E-03	100.0	1000000	1.72		17173

Package Totals	Weight (g)	7.12 E-02	Percentage (%)	100	PPM	1000000
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ADI Proprietary

Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	NiPdAu
MS Number	MS010758B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.35 E-02	87.70	877000	47.10		470965
Thermosets	Epoxy Resin	Proprietary	1.91 E-03	5.00	50000	2.69		26851
Thermosets	Phenol Resin	Proprietary	1.91 E-03	5.00	50000	2.69		26851
Thermosets	Epoxy Cresol Novolac	29690-82-2	7.65 E-04	2.00	20000	1.07		10740
Other inorganic materials	Carbon Black	1333-86-4	1.15 E-04	0.30	3000	0.16		1611
Subtotal			3.82 E-02	100	1000000	53.70		537018

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.74 E-02	97.57	975706	38.43		384328
Copper & its alloys	Iron	7439-89-6	6.39 E-04	2.28	22789	0.90		8977
Copper & its alloys	Zinc	7440-66-6	3.54 E-05	0.13	1263	0.05		497
Copper & its alloys	Phosphorus	7723-14-0	6.80 E-06	0.02	242	0.01		95
Subtotal			2.81 E-02	100.00	1000000	39.39		393898

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Nickel & its alloys	Nickel	7440-02-0	5.11 E-04	97.27	972697	0.72		7168
Precious metals	Palladium	7440-05-3	1.19 E-05	2.26	22621	0.02		167
Precious metals	Gold	7440-57-5	2.46 E-06	0.47	4683	0.003		35
Subtotal			5.25 E-04	100	1000000	0.74		7369

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.80 E-04	99.99	1000000	0.25		2533

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	3.25 E-03	100.0	1000000	4.56		45596

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.52 E-04	77.71	777100	1.06		10558
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	3.01 E-05	3.11	31100	0.04		423
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	3.01 E-05	3.11	31100	0.04		423
Other organic materials	Butyrolactone, gamma-	96-48-0	3.01 E-05	3.11	31100	0.04		423
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	3.01 E-05	3.11	31100	0.04		423
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.01 E-05	3.11	31100	0.04		423
Other organic materials	Organosilane	TS ref# 10001	3.01 E-05	3.11	31100	0.04		423
Other inorganic materials	Copper(II) oxide	1317-38-0	3.01 E-05	3.11	31100	0.04		423
Other organic materials	Epoxy resin modifier	TS ref# 10038	5.03 E-06	0.52	5200	0.01		71
Subtotal			9.68 E-04	100	1000000	1.36		13587

Package Totals			Weight (g) 7.12 E-02			Percentage (%) 100.00		PPM 1000000
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ADI Proprietary

Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	SnPb
MS Number	MS011536A

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-96-0	3.58 E-02	86.20	862000	50.27	502730
Thermosets	Epoxy resin	Proprietary	3.12 E-03	7.50	75000	4.37	43741
Thermosets	Phenol Novolac	9003-35-4	1.66 E-03	4.00	40000	2.33	23329
Other inorganic materials	Antimony Trioxide	1309-64-4	6.23 E-04	1.50	15000	0.87	8748
Thermosets	Brominated Resin	40039-93-8	2.08 E-04	0.50	5000	0.29	2916
Other inorganic materials	Carbon Black	1333-86-4	1.25 E-04	0.30	3000	0.17	1750
Subtotal			4.15 E-02	100	1000000	58.32	583214

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.40 E-02	99.90	999000	33.69	336855
Copper & its alloys	Zirconium	7704-99-6	2.40 E-05	0.10	1000	0.03	337
Subtotal			2.40 E-02	100.00	1000000	33.72	337192

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.43 E-04	100.0	1000000	0.34	3406

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.16 E-03	85.0	850000	1.63	16308
Tin & its alloys	Lead	7439-92-1	2.05 E-04	15.0	150000	0.29	2878
Subtotal			1.37 E-03	100.0	1000000	1.92	19186

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.00 E-04	99.99	1000000	0.42	4212

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.63 E-03	100.0	1000000	3.69	36925

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Dioxide	14808-60-7	5.64 E-04	49.90	499000	0.79	7917
Organic materials	Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	9003-36-5	2.26 E-04	20.00	200000	0.32	3173
Organic materials	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8	2.26 E-04	20.00	200000	0.32	3173
Others	Aromatic Amine	Proprietary	5.65 E-05	5.00	50000	0.08	793
Glass	Glass	65997-17-3	5.65 E-05	5.00	50000	0.08	793
Organic materials	Reaction product: bisphenol-A-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	25068-38-6	1.13 E-06	0.10	1000	0.002	16
Subtotal			1.13 E-03	100.00	1000000	1.59	15865

Package Totals			Weight (g)	7.12 E-02		Percentage (%)	100.00	PPM	1000000
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